# **DMC904E2**

# Silicon NPN epitaxial planar type

For high frequency amplification

#### ■ Features

- High transition frequency f<sub>T</sub>
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Basic Part Number

Dual DSC2G02 (Individual)

# ■ Packaging

DMC904E20R Embossed type (Thermo-compression sealing): 8 000 pcs / reel (standard)

# ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	30	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	3	V	
Collector current	$I_{C}$	15	mA	
Total power dissipation	$P_{T}$	125	mW	
Junction temperature	$T_j$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

## ■ Package

#### • Code

SMini6-F3-B

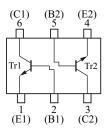
Package dimension clicks here.  $\rightarrow$ 

#### • Pin Name

1: Emitter (Tr1) 4: Emitter (Tr2) 2: Base (Tr1) 5: Base (Tr2) 3: Collector (Tr2) 6: Collector (Tr1)

# ■ Marking Symbol: D0

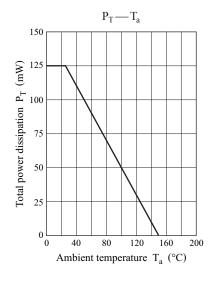
#### ■ Internal Connection

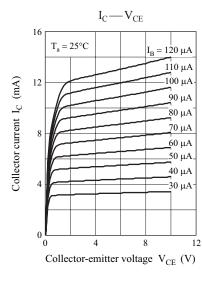


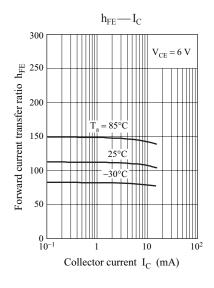
### ■ Electrical Characteristics $T_a = 25$ °C±3°C

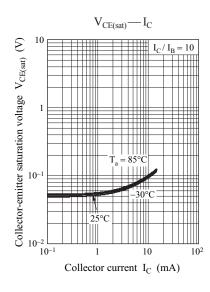
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu A, I_E = 0$	30			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_E = 10 \mu A, I_C = 0$	3			V
Base-emitter voltage	$V_{BE}$	$V_{CE} = 6 \text{ V}, I_C = 1 \text{ mA}$		0.72		V
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$	65		260	_
Transition frequency	$f_T$	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$	450	650		MHz
Reverse transfer capacitance (Common emitter)	C <sub>re</sub>	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 10.7 \text{ MHz}$		0.6		pF
Power gain	PG	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$		24		dB
Noise figure	NF	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$		3.3		dB

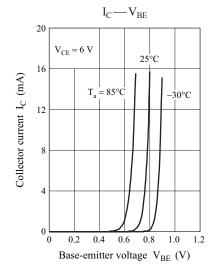
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

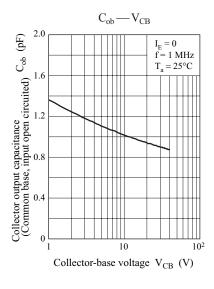


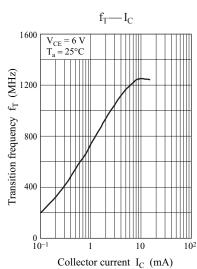












2 Ver. CED

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